



Device Material Content

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Package: 256 caBGA
Total Device Weight 327.63 Milligrams

Package Code:

BG256

Products:

LCMX03D

Assembly: ASEK

Size (mm): 14 x 14

Lead pitch (mm): 0.8

MSL: 3

Reflow max (°C): 260

	% of Total Pkg. Wt.	Weight (mg)	% of Total Pkg. Wt.	Weight (mg)	Substance	CAS #	% of Subst.	Notes / Assumptions:
Die	4.73%	15.50			Silicon chip	7440-21-3	100.00%	Die size: 3.95 x 5.55 mm
Mold Compound	32.01%	104.87	24.01% 4.00% 1.92% 1.92% 0.16%	78.656 13.109 6.292 6.292 0.524	Aluminum oxide Silica(Fused) Epoxy resin Phenol resin Carbon Black	1344-28-1 60676-86-0 - - 1333-86-4	75.00% 12.50% 6.00% 6.00% 0.50%	Mold Compound: Kyocera KE-G1250AHT
D/A Epoxy	1.70%	5.57	1.36% 0.34%	4.456 1.114	Silver Esters & resins	7440-22-4 -	80.00% 20.00%	Die attach epoxy: Henkel (Ablebond) 2100A
Wire	0.57%	1.87	0.55% 0.02% 0.00%	1.803 0.058 0.007	Copper (Cu) Palladium (Pd) Gold (Au)	7440-50-8 7440-05-3 7440-57-5	96.55% 3.10% 0.35%	Au coated PCC, 0.02mm dia
Solder Balls	21.84%	71.55	21.08% 0.66% 0.11%	69.050 2.147 0.358	Tin (Sn) Silver (Ag) Copper (Cu)	7440-31-5 7440-22-4 7440-50-8	96.50% 3.00% 0.50%	SAC305
Substrate	13.70%	44.90	4.38% 9.32%	14.366 30.529	BT Resins Glass fiber	- 65997-17-3	32.00% 68.00%	BT Resin CCL-HL832NX-A
Solder mask	6.66%	21.82	1.57% 0.39% 0.98% 0.98% 1.17% 0.98% 0.59%	5.131 1.282 3.208 3.208 3.847 3.208 1.938	Solvent naphtha (petroleum) Naphthalene Phosphin oxide derivative Talc (containing no asbestiform fibers) Dipropylene glycol monomethyl Ether Epoxy Resin Barium Sulfate	64742-94-5 91-20-3 - 14807-96-6 34590-94-8 85954-11-6 7727-43-7	23.52% 5.87% 14.70% 14.70% 17.63% 14.70% 8.88%	Solder mask PSR4000 AUS 320
Foil	18.79%	61.56	17.51% 1.06% 0.23%	57.356 3.460 0.748	Copper Nickel plating Gold plating	7440-50-8 7440-02-0 7440-57-5	93.17% 5.62% 1.21%	

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.

Constituent substances and proportions in epoxy materials are before curing.

The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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